

STH260N6F6-6

N-channel 60 V, 1.7 mΩ typ., 180 A STripFET™ VI DeepGATE™ Power MOSFET in H²PAK-6 package

Datasheet - preliminary data

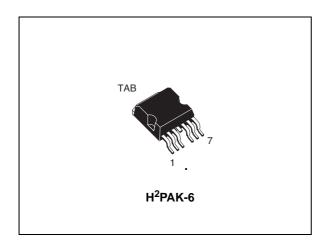
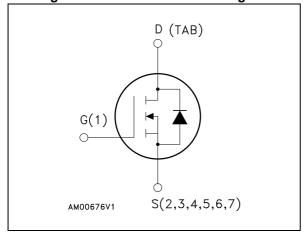


Figure 1. Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max	I _D
STH260N6F6-6	60 V	$2.4~\text{m}\Omega$	180 A

- · Low gate charge
- Very low on-resistance
- High avalanche ruggedness

Applications

· Switching applications

Description

This device is an N-channel Power MOSFET developed using the 6^{th} generation of STripFETTM DeepGATETM technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest R_{DS(on)} in all packages.

Table 1. Device summary

	Order code	Marking	Package	Packaging
ĺ	STH260N6F6-6	STH260N6F6-6 260N6F6		Tape and reel

Contents STH260N6F6-6

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STH260N6F6-6 Electrical ratings

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source voltage	60	V
V _{GS}	Gate-source voltage	± 20	V
I _D	Drain current (continuous) at T _C = 25 °C	180	Α
I _D	Drain current (continuous) at T _C = 100 °C	180	Α
I _{DM} ⁽¹⁾	Drain current (pulsed)	720	Α
P _{TOT}	Total dissipation at T _C = 25 °C	300	W
	Derating factor	2	W/°C
T _{stg}	Storage temperature - 55 to 175		°C
T _j	Operating junction temperature	- 55 10 175	
E _{AS} ⁽²⁾ Single pulse avalanche energy		900	mJ

^{1.} Current limited by package.

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-case}	Thermal resistance junction-case max.	0.5	°C/W
R _{thj-pcb} ⁽¹⁾	Thermal resistance junction-pcb max.	35	°C/W

^{1.} When mounted on FR-4 board of 1 inch², 2 oz Cu.

^{2.} Starting Tj=25 °C, I_{AV} = 60 A, L = 1.1 mH

Electrical characteristics STH260N6F6-6

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage (V _{GS} = 0)	I _D = 250 μA	60			V
1	Zero gate voltage	V _{DS} = 60 V			1	μΑ
I _{DSS} drain cu	drain current (V _{GS} = 0)	V _{DS} = 60 V, T _C =125 °C			100	μΑ
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 20 V			± 100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2		4	V
R _{DS(on)}	Static drain-source on- resistance	V _{GS} = 10 V, I _D = 60 A		1.7	2.4	μΩ

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C _{iss}	Input capacitance			11800		pF
C _{oss}	Output capacitance	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz,}$ $V_{GS} = 0$	1	1235	-	pF
C _{rss}	Reverse transfer capacitance			488		pF
Q_g	Total gate charge	$V_{DD} = 30 \text{ V}, I_{D} = 120 \text{ A},$ $V_{GS} = 10 \text{ V}$ (see Figure 14)		183		nC
Q_{gs}	Gate-source charge		-	53	-	nC
Q _{gd}	Gate-drain charge			41		nC

Table 6. Switching times

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Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t _{d(on)}	Turn-on delay time	$V_{DD} = 30 \text{ V}, I_{D} = 60 \text{ A}$ $R_{G} = 4.7 \Omega V_{GS} = 10 \text{ V}$ (see Figure 13)	-	31.4	-	ns
t _r	Rise time		-	165	-	ns
t _{d(off)}	Turn-off-delay time		-	144.4	-	ns
t _f	Fall time		-	62.6	-	ns



Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		-		180	Α
I _{SDM} ⁽¹⁾	Source-drain current (pulsed)		-		720	Α
V _{SD} (2)	Forward on voltage	$I_{SD} = 180 \text{ A}, V_{GS} = 0$	-		1.1	V
t _{rr}	Reverse recovery time	I _{SD} = 120 A, V _{DD} = 48 V	-	55.6		ns
Q _{rr}	Reverse recovery charge	di/dt = 100 A/μs, Τ _i = 150 °C	-	116		nC
I _{RRM}	Reverse recovery current	(see Figure 15)	-	3.8		Α

^{1.} Current limited by package.

^{2.} Pulsed: pulse duration = $300 \mu s$, duty cycle 1.5%

Electrical characteristics STH260N6F6-6

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance

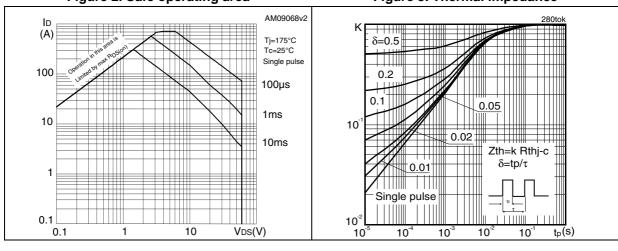


Figure 4. Output characteristics

Figure 5. Transfer characteristics

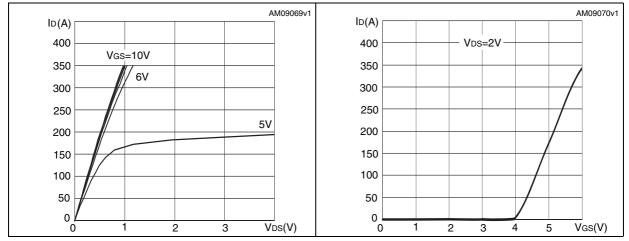
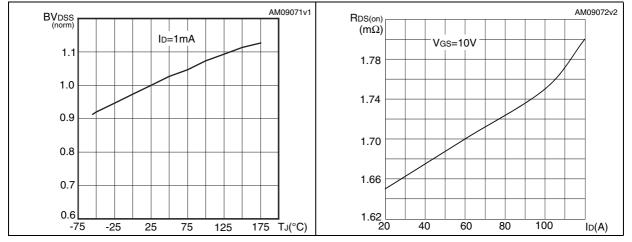


Figure 6. Normalized B_{VDSS} vs. temperature

Figure 7. Static drain-source on-resistance



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Figure 8. Gate charge vs. gate-source voltage

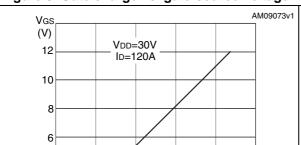


Figure 9. Capacitance variations

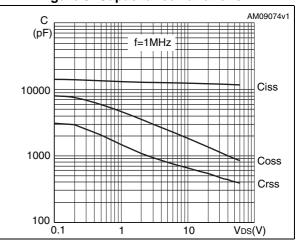


Figure 10. Normalized gate threshold voltage vs. temperature

100

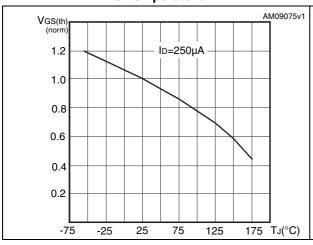
150

200

Qg(nC)

50

Figure 11. Normalized on-resistance vs. temperature



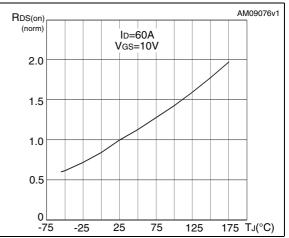
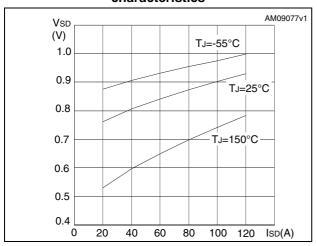


Figure 12. Source-drain diode forward characteristics



Test circuits STH260N6F6-6

3 Test circuits

Figure 13. Switching times test circuit for resistive load

Figure 14. Gate charge test circuit

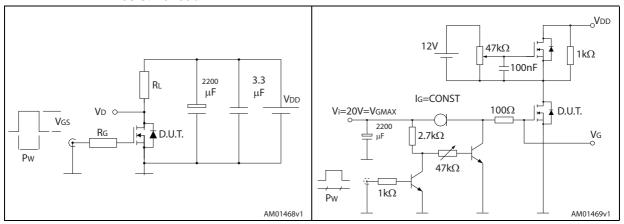


Figure 15. Test circuit for inductive load switching and diode recovery times

Figure 16. Unclamped inductive load test circuit

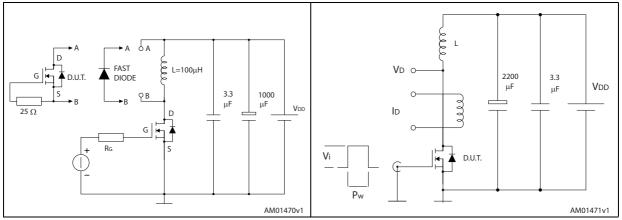
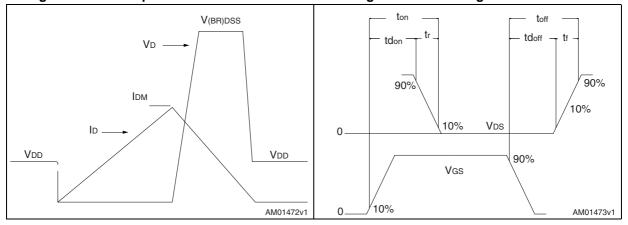


Figure 17. Unclamped inductive waveform

Figure 18. Switching time waveform



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4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

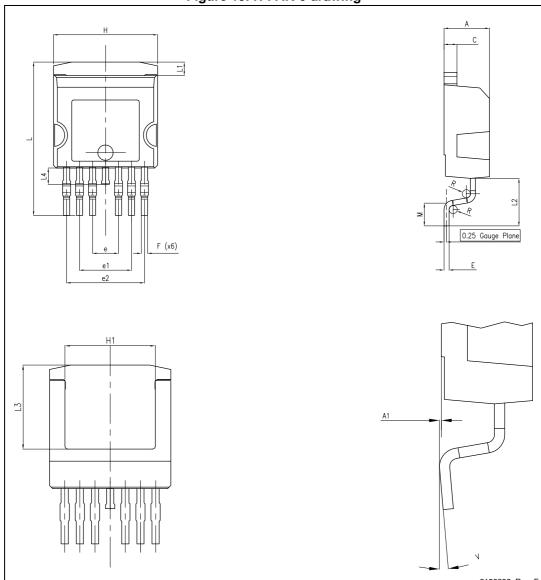


Figure 19. H²PAK-6 drawing

Table 8. H²PAK-6 mechanical data

Dim	mm		
Dim.	Min.	Тур.	Max.
А	4.30		4.80
A1	0.03		0.20
С	1.17		1.37
е	2.34		2.74
e1	4.88		5.28
e2	7.42		7.82
E	0.45		0.60
F	0.50		0.70
Н	10.00		10.40
H1	7.40	-	7.80
L	14.75		15.25
L1	1.27		1.40
L2	4.35		4.95
L3	6.85		7.25
L4	1.5		1.75
М	1.90		2.50
R	0.20		0.60
V	0°		8°

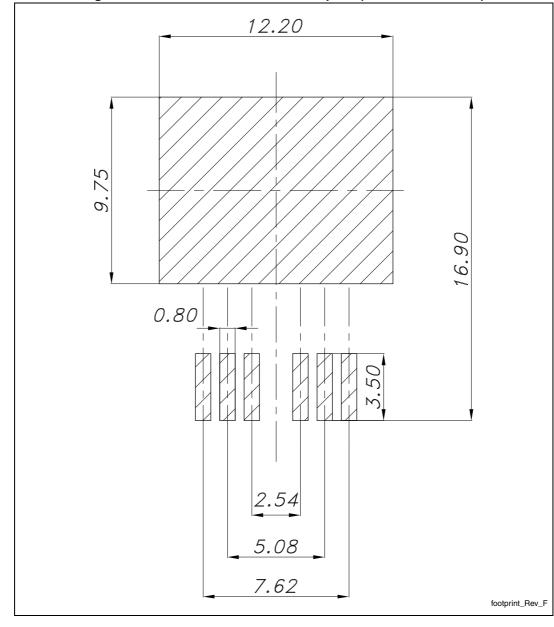


Figure 20. H²PAK-6 recommended footprint (dimensions in mm)

Revision history STH260N6F6-6

5 Revision history

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Table 9. Document revision history

Date	Revision	Changes
05-Jul-2012	2	First release.
06-Mar-2014	2	Modified <i>Table 2: Absolute maximum ratings</i> . Minor text changes.

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